

RELIABILITY REPORT
FOR
MAX3738ETG+T
PLASTIC ENCAPSULATED DEVICES

January 17, 2012

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.
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Approved by
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Quality Assurance
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Conclusion

The MAX3738ETG+T successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

Table of Contents

I.Device Description	V.Quality Assurance Information
II.Manufacturing Information	VI.Reliability Evaluation
III.Packaging Information	IV.Die Information
.....Attachments	

I. Device Description

A. General

The MAX3738 is a +3.3V laser driver designed for multirate transceiver modules with data rates from 1Gbps to 4.25Gbps. Lasers can be DC-coupled to the MAX3738 for reduced component count and ease of multirate operation. Laser extinction ratio control (ERC) combines the features of automatic power control (APC), modulation compensation, and built-in thermal compensation. The APC loop maintains constant average optical power. Modulation compensation increases the modulation current in proportion to the bias current. These control loops, combined with thermal compensation, maintain a constant optical extinction ratio over temperature and lifetime. The MAX3738 accepts differential data input signals. The wide 5mA to 60mA (up to 85mA AC-coupled) modulation current range and up to 100mA bias current range, make the MAX3738 ideal for driving FP/DFB lasers in fiber optic modules. External resistors set the required laser current levels. The MAX3738 provides transmit disable control (TX_DISABLE), single-point fault tolerance, bias-current monitoring, and photocurrent monitoring. The device also offers a latched failure output (TX_FAULT) to indicate faults, such as when the APC loop is no longer able to maintain the average optical power at the required level. The MAX3738 is compliant with the SFF-8472 transmitter diagnostic and SFP MSA timing requirements. The MAX3738 is offered in a 4mm x 4mm, 24-pin thin QFN package and operates over the extended -40°C to +85°C temperature range.

II. Manufacturing Information

A. Description/Function:	155Mbps to 4.25Gbps SFF/SFP Laser Driver with Extinction Ratio Control
B. Process:	CB53
C. Number of Device Transistors:	4060
D. Fabrication Location:	USA
E. Assembly Location:	China, Malaysia and Thailand
F. Date of Initial Production:	January 24, 2004

III. Packaging Information

A. Package Type:	24-pin TQFN 4x4
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-9000-3889
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	48°C/W
K. Single Layer Theta Jc:	3°C/W
L. Multi Layer Theta Ja:	36°C/W
M. Multi Layer Theta Jc:	3°C/W

IV. Die Information

A. Dimensions:	90.94 X 66.14 mils
B. Passivation:	Si ₃ N ₄ /SiO ₂ (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	Metal1 = 0.6 / Metal2 = 0.6 / Metal3 = 1.2 microns (as drawn)
F. Minimum Metal Spacing:	Metal1 = 0.4 / Metal2 = 0.4 / Metal3 = 1.2 microns (as drawn)
G. Bondpad Dimensions:	
H. Isolation Dielectric:	SiO ₂
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

- A. Quality Assurance Contacts: Richard Aburano (Manager, Reliability Engineering)
Don Lipps (Manager, Reliability Engineering)
Bryan Preeshl (Vice President of QA)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 2454 \times 238 \times 2} \text{ (Chi square value for MTTF upper limit)}$$

(where 2454 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 8.2 \times 10^{-9}$$

$$\lambda = 8.2 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maxim-ic.com/qa/reliability/monitor>. Cumulative monitor data for the CB53 Process results in a FIT Rate of 0.46 @ 25C and 7.85 @ 55C (0.8 eV, 60% UCL)

B. E.S.D. and Latch-Up Testing (lot JJR1AA038A, D/C 1117)

The HD56-1 die type has been found to have all pins able to withstand a HBM transient pulse of +/- 2500V per JEDEC JESD22-A114. Latch-Up testing has shown that this device withstands a current of +/- 250mA and overvoltage per JEDEC JESD78.

Table 1
Reliability Evaluation Test Results

MAX3738ETG+T

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note 1)	Tj ~ 150C	DC Parameters	80	0	JJR0FZ001F, D/C 0940
	Biased	& functionality	78	0	JJR0FQ003F, D/C 0940
	Time = 192 hrs.		80	0	JJR0FQ002F, D/C 0940

Note 1: Life Test Data may represent plastic DIP qualification lots.